

Integrated Photonics and Optical Communication

Hall N1**Integrated Photonics and
Optical Communication**

**"Showing a Complete Industry Chain from
Optical Chips, Optical Devices, and
Optical Modules to System Solutions"**

Leveraging the strengths of the Yangtze River Delta region—the core optoelectronics industry belt of East China, we aggregate resources across semiconductors, optical communications, automotive optics, and frontier photonics.

Concurrent forums:

- AI Computing & Optical Interconnect Forum
- Silicon Photonics Integration & Optoelectronics Convergence Forum
- New Products and Application Innovations Launch



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Mini Program

Integrated Photonics and Optical Communication—Why Choose Laser World of Photonics Shanghai?

Our Five Core Advantages—Not to Be Missed



Rooted in East China's Photonics Hub: Direct Access to Upstream and Downstream Resources

Centering on Shanghai, Suzhou, Wuxi, Hangzhou, and Hefei, the Yangtze River Delta region accounts for over 60% of China's optical communication capacity. With a high concentration of silicon photonics and thin-film lithium niobate (TFLN) suppliers, a complete industrial loop—from wafers and photonic chips to packaging and high-speed optical modules—is achievable within a 100km radius. Suzhou hosts global optical module leaders, while Shanghai Zhangjiang and Wuxi have established TFLN pilot lines. This proximity attracts a vast number of suppliers, foundries, and end customers to the exhibition.



Connecting Innovation Hubs: Bridging the "R&D — Pilot — Mass Production" Path

The Yangtze River Delta region clusters national-level photonics research platforms, as well as laboratories and pilot lines for TFLN, silicon photonics, quantum photonics, and high-speed coherent optical communications. Concurrent forums invite academicians, university professors, and pilot-line experts to empower industry-academia-research collaboration, process verification, and technology commercialization. Shanghai, Jiangsu, Zhejiang, and Anhui have listed integrated photonics, optical communications, and quantum technology as key industries in their 15th Five-Year Plans. The exhibition links industrial parks, sci-tech innovation funds, and industrial policies to help enterprises accelerate capacity deployment.



20+ Years International Platform: Driving the "Domestic Presence + Global Expansion"

Leveraging the deep heritage of the parent exhibition and the global Laser World of Photonics network, the exhibition has been rooted in China for 22 years. It has amassed over 200,000 professional visitors, covering the entire domestic optoelectronics industry chain and reaching 22 countries and regions. With over 71% of visitors from East China, it precisely targets the industry heartland. The upgraded XMatch business matching system 24X7 precise connections, providing a one-stop channel for both domestic presence and global expansion.



Hall N1 + Prime Year-Opening Slot: Maximizing Brand Exposure

March is a critical industry kick-off, offering a golden window for companies to plan annual technology iterations, expand business, and finalize supply chain partnerships. Decision-makers, R&D engineers, and procurement heads all present. Located in the Hall N1—the high-traffic core—the exhibition features dedicated TFLN and quantum photonics zones. It serves as a benchmark for exhibiting next-generation integrated photonics in East China, boosting brand visibility and leadership.



Multiple Cutting-Edge Technology Forums: Building a Hub for Deep Exchange

Concurrent forums cover AI computing & optical interconnect, devices-to-networks collaborative innovation, and quantum computing & photonic chips, bringing together academicians, industry CTOs, research experts, and investors. Focusing on TFLN, silicon photonics integration, high-speed optical interconnects, automotive optical communication, and quantum photonics, the exhibition offers exclusive slots for corporate speeches and new product launches to enhance brand reach among technical decision-makers and R&D talents.

Previous Exhibitors

*In no particular order.

Exhibition Scope

Integrated Photonic Chips (Core Foundation of Optoelectronics Convergence)

Active device chips: Laser chips (VCSEL, DML, EML, EEL, DFB), detector chips (PIN, APD), amplifier chips (LA, TIA, LD Driver), DSP chips, heterogeneously integrated optoelectronic chips.
Passive device chips: PLC chips, AWG chips, optical switch chips, wavelength division multiplexing chips, TFLN modulator chips, silicon-based passive waveguide chips, photonic coupling chips.

Optical Components & Devices (Optoelectronic Packaging Integration)

Active optical devices: VCSELs, semiconductor lasers, narrow-linewidth tunable light sources, DFB/EML lasers; optical amplifiers, semiconductor optical amplifiers; PIN/APD photodetectors; TOSA, ROSA, BOSA, coherent optical engines; LCOS spatial light modulators, high-speed electro-optic modulators.
Passive optical devices: Fiber optic connectors, optical isolators, fiber couplers, PLC splitters, optical switches, WDM/DWDM devices, optical attenuators; ceramic sleeves, precision optical coupling assemblies, high-speed optoelectronic interconnect components.

Optical Modules (Core Optoelectronic Interfaces for Computing Networks)

100G/400G/800G/1.6T/3.2T short-reach & coherent optical modules, ultra-broadband AWG optical modules, pluggable optical modules, silicon photonics integration optical modules, co-packaged optics (CPO) optical engines, automotive optical communication modules.

Optical Fiber & Cable Industry Chain

Optical fiber preforms, fiber coating materials, fiber bragg gratings, fiber protective sleeves; single-mode/multi-mode fibers, erbium-doped fibers, hollow-core fibers, optoelectronic composite cables, submarine optical cables; optical crystals, optoelectronic thin films, bonded substrates, micro-nano optical materials, cable processing, fiber polishing, testing & inspection equipment.

System Equipment (Optoelectronics Convergence Application Terminals)

Optical communication transmission equipment: Optical circuit switches, optical transceivers, integrated optical distribution/transmission systems, silicon photonic coupling systems, optical transmitters.
Data center & computing network equipment: Ethernet switches, optical circuit switch cabinets, high-power optical amplification systems, PoE switches, industrial optoelectronic switching equipment.
Wires & cables: High-speed active cables, optoelectronic composite cables, coaxial cables, network patch cords.

Test & Measurement Instrumentation (Optoelectronic Performance Verification)

Optical network testers, optical spectrum analyzers, oscilloscopes, high-performance bit error rate testers, wavelength sweep test systems, optoelectronic network analyzers, signal quality analyzers, fiber fusion splicers, chip probe test systems.

Manufacturing Equipment & Process Support

Photonic chip manufacturing equipment: Epitaxy equipment, lithography machines, etching machines, bonding equipment, wafer dicing equipment, coating equipment.
Optoelectronic packaging equipment: Automatic eutectic die bonders, optical coupling machines, dispensers, die attach equipment, high-precision micro-assembly systems.
Semiconductor optoelectronic materials: Indium phosphide, gallium arsenide, silicon-based materials, lithium niobate single-crystal thin films, photoresists, specialty adhesives.

Frontier Optoelectronic Convergence

Quantum photonic devices, microwave optoelectronic integrated systems, optoelectronic sensing chips, automotive high-speed optical interconnects, precision measurement photonic systems.

Grand Launch! Special Thin-Film Lithium Niobate (TFLN) Exhibition Zone

Core advantages: Relying on the existing optical equipment and laser industry, the zone achieves full-chain coverage from "material substrates — manufacturing equipment — chip devices — scenario applications," becoming a domestic full-chain lithium niobate exhibition area.

Spatial Layout



Exhibitors



Focusing on TFLN Innovation, Ushering in a New Era of High-speed Optical Interconnects

Concurrent Events on Integrated Photonics and Optical Communication

As the restructuring driven by large AI models breaks through traditional bandwidth bottlenecks, competition in the optical communication industry has shifted from a single device to system-level ecological synergy. This year's Laser World of Photonics Shanghai plans to deeply deconstruct the core issues of the optical communication industry chain: from breakthroughs in silicon photonics integration and CPO to the architectural reshaping of AI computing networks and the rapid translation of cutting-edge research into practical outcomes, creating a full-scenario technology feast.



2027 Concurrent Event Keywords

AI Computing Optical Interconnect **High-speed Optical Devices** **Photonic Chips**
Co-packaged Optics/Near-Packaged Optics (CPO/NPO)

Optical Interconnects **Data Centers** **Thin-film Lithium Niobate**

Specialty Fibers **Silicon Photonics Technology** **Automotive Optical Communication**
800G/1.6T/3.2T **Hollow-core Fibers** **Multi-core Fibers** **Optical Modules**

The 2026 Integrated Photonics and Optical Communication event spanned **2.5 days**, featuring **3 themed events**, **19 high-quality keynote speeches**, **15 new product roadshows**, and **1 in-depth roundtable discussion**, achieving an overall satisfaction rate of **95%**.

In 2027, the event will continue to expand in breadth and depth, with academic conferences, professional forums, and new product roadshows working in synergy to provide a platform for in-depth industry-academia-research dialogue from optoelectronic chips to intelligent computing centers.



Core Event Themes

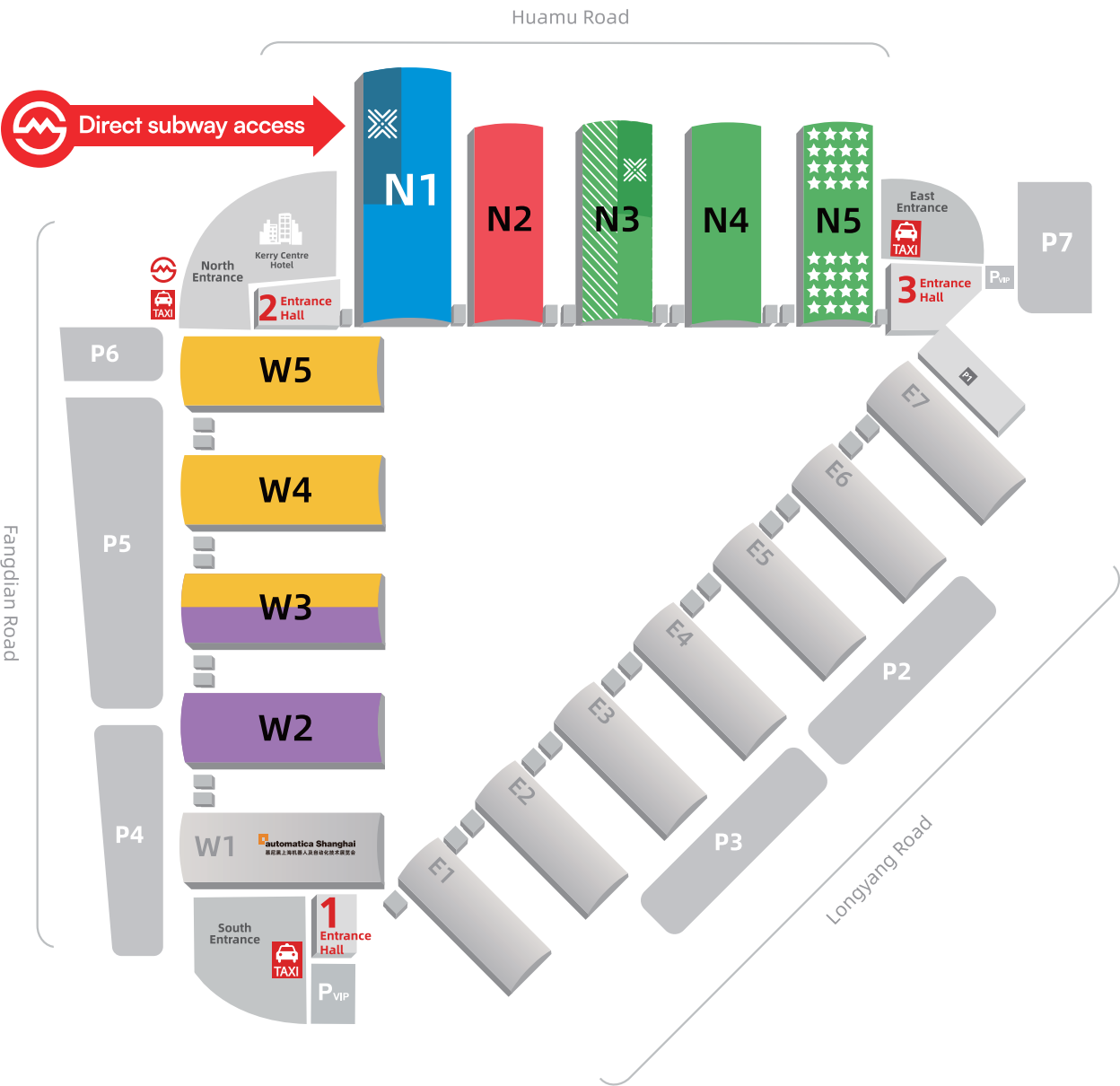
- AI Computing & Optical Interconnect Forum
- New Products and Application Innovations Launch
- Silicon Photonics Integration & Optoelectronics Convergence Forum

Partners



Layout

Hall N1 — Traffic hub with high visitor flow



W2/W3 Laser and Laser Systems for Production Engineering	W3/W4/W5 Lasers and Optoelectronics	N1 Integrated Photonics and Optical Communication	N2 Optical Metrology and Quality Assurance
N3 Infrared Technology and Application	N3/N4 Optics	N5 Manufacturing Technology for Optics	Dedicated Quantum Zone Biomedical Photonics Zone

Key Previous Visitors

Electrical engineering/Electronics industry

- Goertek Inc.
- FURUKAWA ELECTRIC CO., LTD.
- Circuit Fabology Microelectronics Equipment
- East China Microelectronics
- China Resources Microelectronics
- Kunshan Q Technology Co., Ltd.
- Chongqing United Microelectronics Center
- Nanya PCB
- Naura Microelectronics
- AAC Technologies
- MITSUBISHI ELECTRIC
- Shanghai Electric
- Shanghai Fudan Microelectronics Group Co., Ltd.
- Shanghai Microelectronics Equipment Co., Ltd.
- Schneider Electric
- Telink Semiconductor
- Tianma Microelectronics Co., Ltd.
- XTool Makeblock Co., Ltd.
- Siemens
- Yandong Microelectronics

Semiconductor

- 3D-micromac AG
- Applied Materials
- ASML
- ASMPT SMT Singapore Pte. Ltd.
- Lattice Semiconductor
- Northern Huachuang
- JCET Group Co., Ltd.
- TDK-Lambda
- Jingce Semiconductor
- Corning
- KLA-Tencor Corporation
- Changelight
- Sunny Semiconductor
- Samsung Electronics
- Hua Hong Grace Semiconductor Limited
- Shanghai Skyverse Semiconductor Technology Co., Ltd.
- Qualcomm
- Hangzhou Guangyan Technology Co., Ltd.
- Empyrean Technology
- HWATSING
- HT-Tech
- HiSilicon (Shanghai) Technologies CO., LTD
- ACM
- Sony Semiconductor Solutions Corporation
- Piotech Inc.
- TongFu Microelectronics
- Infineon
- Semiconductor Manufacturing International (Beijing)Corporation

Communication

- Alibaba Information Port
- Beijing Optics Microelectronics
- Beijing Academy of Quantum Information Sciences
- Eoptolink Technology Inc., Ltd.
- TAIHAN Fiberoptics
- Hangzhou Futong Communication (Futong Group)
- EVERFINE
- Hengdong Optical Communication
- Huacan Telecommunication
- Laser Link
- China Unicom 5G Yangtze River Delta Innovation Center
- Shanghai GTX Semiconductor
- Shanghai Huawei Technologies Co., Ltd.
- TFC
- Accelink
- Xiaomi Corporation
- Changguang Communication Technology
- CECLOUD Computing Technology Co., Ltd
- China Telecommunication Technology Labs
- China Mobile Research Institute
- Zhongji Innolight
- EverProX Technologies
- ZTT Fiber Co., Ltd.
- Shanghai Telecom Engineering Co., Ltd.

Automotive Industry

- Autoliv
- DENSO
- HYUNDAI MOBIS
- BYD
- ZF Automotive Technology (Zhangjiagang) Co., Ltd.
- Continental Automotive
- Desay SV Automotive Co., Ltd.
- Dongfeng Motor Corporation
- Fuyao Group
- GRIPP
- HUAYU Electric Drive
- Geely Auto
- Magna (Taicang) Automotive Technology Co., Ltd.
- Ningbo JoysonQuin Automotive Systems Holding Co., Ltd.
- CATL
- SAIC Motor
- Stellantis
- Tuopu Group
- Tesla
- NIO
- Bosch Automotive Systems (Wuxi) Co., Ltd.
- XPeng Motors
- Yanfeng/Yanfeng Plastic Omnium
- Sanhua Automotive

Aerospace Industry

- Beijing Aeronautical Precision Machinery Institute
- Beijing Aerospace Era Optoelectronics Technology Co., Ltd.
- Beijing Institute of Spacecraft Environment Engineering
- Guizhou Space Appliance Co., Ltd.
- China Leihua Electronic Technology Research Institute
- AVIC Xi'an Flight Automatic Control Research Institute
- CASIC Defense Technology Research and Test Center
- Honeywell International Inc.
- Shanghai Academy of Spaceflight Technology
- Shanghai Aerospace Control Technology Institute (Aerospace No.803 Institute)
- AECC Shenyang Liming Aero-engine Co., Ltd.
- Shenyang Xinghua Aero-Electric Appliance Co., Ltd.
- Galaxy Space
- Changguang Satellite Technology Co., Ltd.
- Shanghai Marine Equipment Research Institute
- The Aviation Industry Corporation of China, Ltd.(AVIC)
- China Aerospace Science and Industry Corporation Limited
- China Aerospace Science and Technology Corporation
- Innovation Academy for Microsatellites of CAS (IAMCAS)
- COMAC
- Zhonghang Electronic Measuring Instruments (XiAn) Co., Ltd.
- Jonhon Optronic Technology Co.,Ltd.
- Aerospace New Sky Technology Co., Ltd.
- Blue Star Light Domain (Shanghai) Aerospace Technology Co., Ltd.

Non-university research institutes

- Attosecond Science Center
- Beijing Institute of Aeronautical Materials
- Beijing Institute of Radio Metrology and Measurement
- IOE CAS
- Dalian Institute of Chemical Physics
- Fraunhofer-ILT
- Songshan Lake Materials Laboratory
- P.N. Lebedev Physical Institute
- Fujian Institute of Research on the Structure of Matter
- Gusu Lab
- National Center for Nanoscience and Technology
- ARIMT
- Hefei National Lab
- Institute of Laser Manufacturing, Henan Academy of Sciences
- Southwestern Institute of Physics
- East China Research Institute of Microelectronics/ ECRIM
- Central China Institute of Photoelectric Technology
- Research Center of Laser Fusion
- Ji Hua Laboratory
- Jinan Institute of Quantum Technology
- Jiangsu CAS Energy and Power Research Center
- Institute of Metal Research
- Technical Institute of Physics and Chemistry CAS
- Lin Gang Laboratory
- Nanjing Institute of Electronic Devices
- Nanjing Institute of Astronomical Optics & Technology, CAS
- Qiyuan Lab
- Shanghai Institute of Safety Production Science
- Shanghai Institute for Biomedical and Pharmaceutical Technologies
- Songshan Lake Materials Laboratory
- Tianfu Jiangxi Laboratory
- Tianfu Xinglong Lake Laboratory
- Wuhan National Laboratory for Optoelectronics
- CETC 2nd Research Institute
- Agency for Science, Technology and Research
- National Key Laboratory for Remanufacturing
- Zhangjiang Laboratory
- Zhejiang Moganshan Institute of Geomagnetism Large-scale Scientific Facility
- Chinese Academy of Sciences
- Institute of Semiconductors, CAS
- Institute of Optics and Electronics, CAS
- Institute of Microelectronics, CAS
- Qingdao Institute of Bioenergy and Bioprocess Technology, CAS
- Shanghai Institute of Ceramics, CAS
- Institute of Biophysics, CAS
- Suzhou Institute of Biomedical Engineering and Technology, CAS
- Suzhou Institute of Nano-Tech and Nano-Bionics, CAS
- CAEP
- ICM, CAEP
- CSPI
- SMDERI
- Deep Space Exploration Lab/DSEL

Colleges/Universities

- Peking University
- Yangtze Delta Institute of Optoelectronics, Peking University
- Beihang University
- Beijing Institute of Technology
- BIT Chongqing Institute of Microelectronics and Microsystems
- Beijing University of Posts and Telecommunications
- Dalian University of Technology
- University of Electronic Science and Technology of China
- Donghua University
- Southeast University
- Saint Petersburg National Research University of Information Technologies, Mechanics and Optics (ITMO)
- Fudan University
- National University of Defense Technology
- Harbin Engineering University
- Harbin Institute of Technology
- Korea Advanced Institute of Science and Technology
- University of Manchester
- Technical University of Munich
- University of Southampton
- Nanjing University of Aeronautics and Astronautics
- Nanjing University of Science and Technology
- University of Oxford
- Shanghai Jiao Tong University
- Wuhan Textile University
- Xidian University
- Northwestern Polytechnical University
- University of Science and Technology of China
- China Agricultural University

*In no particular order.